

PTO-1449		O P E		Attorney's Docket Number RD27416-2	Serial Number 10/638,099	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		LIST OF ITEMS		Name of Applicant Gallucci et al.		
		MAY 11 2006		Filing Date 08/07/2003	Group Art 1711	
(Use several sheets if necessary)		U.S. PATENT DOCUMENTS				
Examiner Initial	Document Number	Date	NAME	Class	Subclass	Filing Date If Appropriate
tt	4754128	6/28/1988	Takeda et al.			
	4942073	6/17/1990	Era et al.			
	5118573	6/2/1992	Tawara et al.			
	5297132	3/22/1994	Takano et al.			
	5330852	7/19/1994	Gerstenberg et al.			
	5512416	4/30/1996	Namba et al.			
	5525379	6/11/1996	Takada et al.			
✓	6183829	2/6/2001	Daecher et al.			
U.S. PATENT APPLICATION PUBLICATIONS						
Examiner Initial	Document Number	Date	NAME	Class	Subclass	Filing Date If Appropriate
tt	2002/0025443	2/28/2002	Ohno			
FOREIGN PATENT DOCUMENTS						
Examiner Initial	Document Number	Date	COUNTRY	Class	Subclass	TRANSLATION YES NO
tt	2099852	07-1993	Canada			x
OTHER INFORMATION (including author, title, date, pertinent)						
tt	Y.Barrell et al., "Expanding Thermal Plasma for Fast Deposition of Scratch-Resistant SiCxHyOz Films", Surface and Coatings Technology 180-181 (2004) 367-371					
	M.F.A.M. van Hest doctoral thesis, "High Rate Deposition of Silicone Oxide Like Films" pages 95-108, 133-154, 167-169 (2002)					
	10/638,145 Non-Final Office Action dated 10/07/2005 (18 pages)					
	10/638,145 Non-Final Office Action dated 03/21/2006 (12 pages)					
	JP03-248337; 11-1991; Abstract Only (2 pages)					
	JP01-232553; 09-1989; Abstract Only (2 pages)					
	JP04-177632; 06-1992; Abstract Only (1 page)					
	JP02-312020; 12-1990; Abstract Only (2 pages)					
	JP60-203489; 10-1985; Abstract Only (1 page)					
	JP63-108540; 05-1988; Abstract Only (2 pages)					
✓	JP63-201929; 08-1988; Abstract Only (2 pages)					
EXAMINER Thao Tran				DATE CONSIDERED 6/20/06		
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